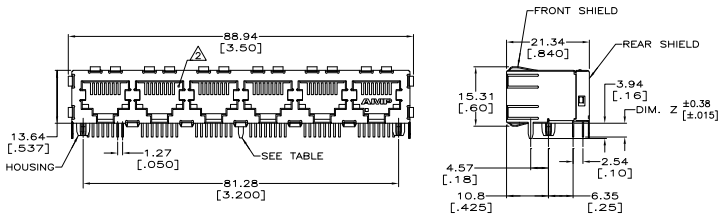
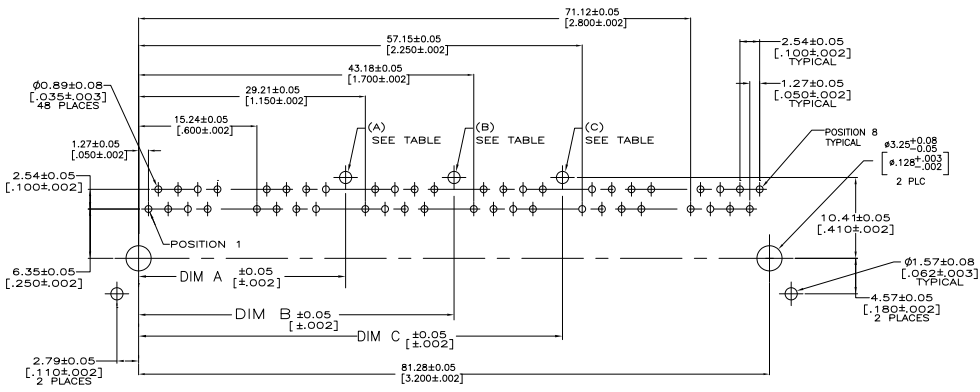


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REV	DATE	DESCRIPTION	BY	CHK	APP
00					
D2		REVISED ECR-08-032447	DW	DZ	SY
D3		REVISED PER ECO-10-000444	DW	KK	HMR



- ▲ MATERIAL: HOUSING - NYLON, BLACK, UL 94V-0. OVERMOLDED TERMINAL ARRAY - PBT, BROWN. TERMINALS - 0.33[0.13] THICK PHOS BRONZE PLATED WITH 1.27 μm[0.00050] MINIMUM HARD GOLD IN LOCALIZED AREA AND 3.81 μm[0.00150] MINIMUM MATTE TIN IN SOLDER AREA OVER 1.27 μm [0.00050] MINIMUM NICKEL UNDERPLATE. SHIELDS - 0.25 [0.01] THICK COPPER ALLOY PLATED WITH 1.27 μm [0.00050] MINIMUM NICKEL AND 2.03 μm [0.00080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- ▲ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- ▲ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



RECOMMENDED PC BOARD LAYOUT
 COMPONENT SIDE (TOP)
 SCALE 4:1

OBSOLETE	Δ	3.56 [140]	26.67 [1050]	40.64 [1600]	54.61 [2150]	3	5406206-3
	Δ	3.56 [140]	NA	40.64 [1600]	NA	1	5406206-2
	Δ	3.56 [140]	NA	NA	NA	NONE	5406206-1

DIM Z	DIM A	DIM B	DIM C	NUMBER OR REAR PCB SHIELD GROUND TABS	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.

INCHES (mm INCHES)

DATE: 108-1163-2

REV: 114-2048

SEE NOTE 1

Customer Drawing: 100779, 5406206

DATE: 2-11-08

REV: 1

APP: D3